Single 2-Input AND Gate

The NLU1G08 MiniGate™ is an advanced high-speed CMOS 2-input AND gate in ultra-small footprint.

The NLU1G08 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.5 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

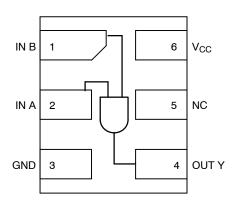


Figure 1. Pinout (Top View)

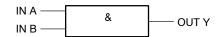


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN B
2	IN A
3	GND
4	OUT Y
5	NC
6	V _{CC}

FUNCTION TABLE

Inj	out	Output
Α	В	Υ
L	L	L
L	Н	L
Н	L	L
Н	Н	Н



ON Semiconductor®

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MARKING DIAGRAMS



UDFN6 1.2 x 1.0 CASE 517AA





ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.45 x 1.0 CASE 517AQ



2 = Device MarkingM = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	٧
V _{IN}	DC Input Voltage	-0.5 to +7.0	٧	
V _{OUT}	DC Output Voltage		-0.5 to +7.0	٧
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current Vo	_{DUT} < GND	±20	mA
Io	DC Output Source/Sink Current		±12.5	mA
I _{CC}	DC Supply Current Per Supply Pin		±25	mA
I _{GND}	DC Ground Current per Ground Pin		±25	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen Inde	ex: 28 to 34	UL 94 V-0 @ 0.125 in	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C	±500	mA	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

2. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T,	_A = 25 °	С	T _A = -	+85°C		55°C to :5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65	0.75 x V _{CC}			0.75 x V _{CC}				V
			2.3 to 5.5	0.70 x V _{CC}			0.70 x V _{CC}				
V _{IL}	Low-Level Input Voltage		1.65			0.25 x V _{CC}		0.25 x V _{CC}		0.25 x V _{CC}	V
			2.3 to 5.5			0.30 x V _{CC}		0.30 x V _{CC}		0.30 x V _{CC}	
V _{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -4$ mA $I_{OH} = -8$ mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 50 \mu A$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 4$ mA $I_{OL} = 8$ mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1.0		10		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		V _{CC}	Test	т,	_A = 25 °	С	T _A = 4	-85°C	T _A = -5 +12		
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	3.0 to	C _L = 15 pF		4.1	8.8		10.5		12.5	ns
t _{PHL}	Input A or B to Output Y	3.6	C _L = 50 pF		5.9	12.3		14		16.5	
		4.5 to 5.5	C _L = 15 pF		3.5	5.9		7.0		9.0	
			C _L = 50 pF		4.2	7.9		9.0		11	
C _{IN}	Input Capacitance				5.5	10		10		10	pF
C _{PD}	Power Dissipation Capacitance (Note 3)	5.0			11						pF

^{3.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

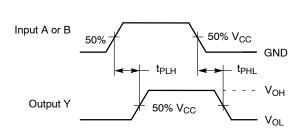
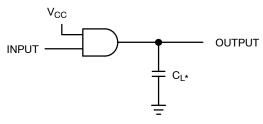


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance.
A 1-MHz square input wave is recommended for propagation delay tests.

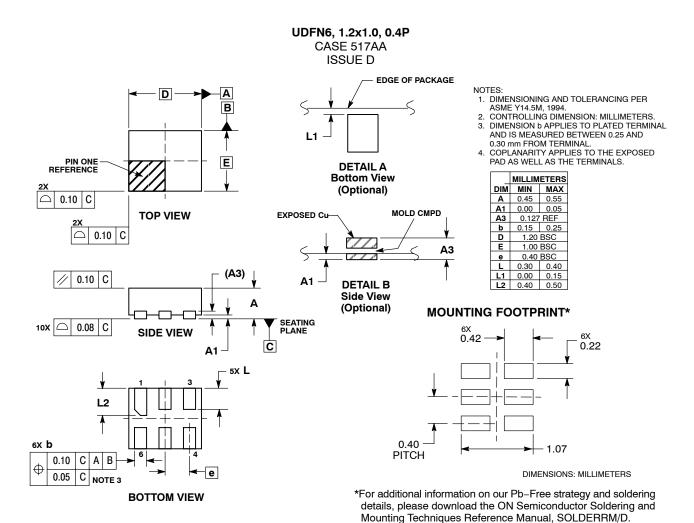
Figure 4. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NLU1G08MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLU1G08AMX1TCG	ULLGA6, 1.45 x 1.0 (Pb-Free)	3000 / Tape & Reel
NLU1G08BMX1TCG	ULLGA6, 1.2 x 1.0 (Pb-Free)	3000 / Tape & Reel
NLU1G08CMX1TCG	ULLGA6, 1.0 x 1.0 (Pb-Free)	3000 / Tape & Reel
NLU1G08AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLU1G08CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

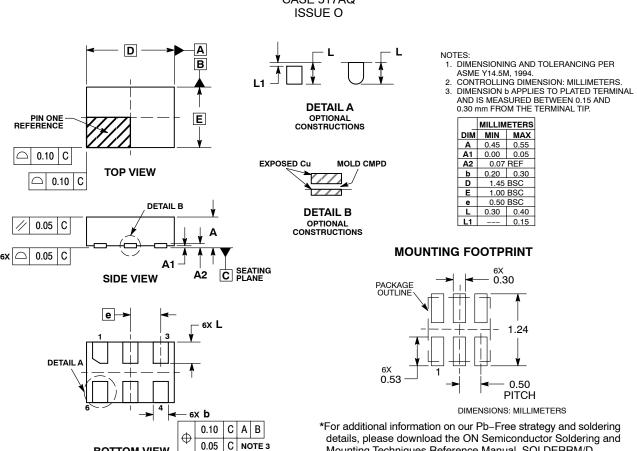
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ ISSUE O

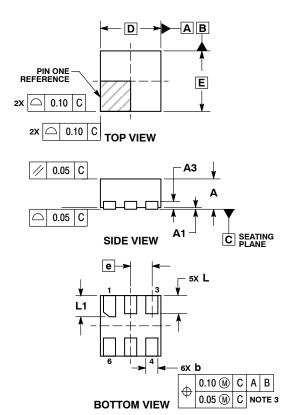


Mounting Techniques Reference Manual, SOLDERRM/D.

BOTTOM VIEW

PACKAGE DIMENSIONS

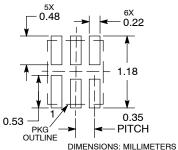
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETER					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
А3	0.13 REF					
b	0.12	0.22				
D	1.00	BSC				
Е	1.00	BSC				
е	0.35 BSC					
L	0.25	0.35				
11	0.30	0.40				

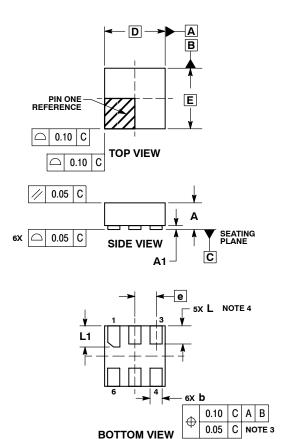
RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

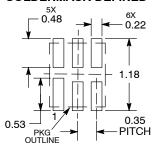
ULLGA6 1.0x1.0, 0.35P CASE 613AD **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS				
DIM	MIN	MAX			
Α	-	0.40			
A1	0.00	0.05			
b	0.12	0.22			
D	1.00	BSC			
Е	1.00	BSC			
е	0.35 BSC				
L	0.25	0.35			
L1	0.30	0.40			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

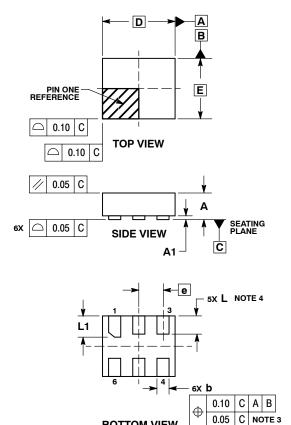


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P CASE 613AE **ISSUE A**

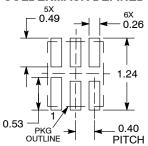


BOTTOM VIEW

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PEACKAGE IS ALLOWED. PACKAGE IS ALLOWED.

	MILLIMETERS				
DIM	MIN	MAX			
Α		0.40			
A1	0.00	0.05			
b	0.15	0.25			
D	1.20	BSC			
E	1.00	BSC			
е	0.40	BSC			
L	0.25	0.35			
L1	0.35	0.45			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

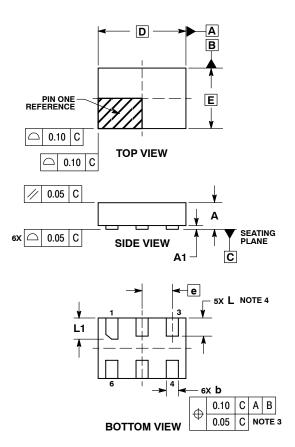


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P CASE 613AF **ISSUE A**

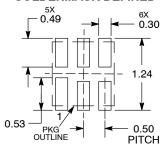


NOTES

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP. A MAXIMUM OF 0.05 PULL BACK OF THE
- PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS				
DIM	MIN	MAX			
Α		0.40			
A1	0.00	0.05			
b	0.15	0.25			
D	1.45	BSC			
Е	1.00	BSC			
е	0.50 BSC				
L	0.25	0.35			
L1	0.30	0.40			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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